

Second edition
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AMENDMENT 1
2023-09

**Building environment design —
Design, dimensioning, installation and
control of embedded radiant heating
and cooling systems —**

Part 6:
Control

AMENDMENT 1

*Conception de l'environnement des bâtiments — Conception,
construction et fonctionnement des systèmes de chauffage et de
refroidissement par rayonnement —*

Partie 6: Contrôle

AMENDEMENT 1



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Part 6: Control

AMENDMENT 1

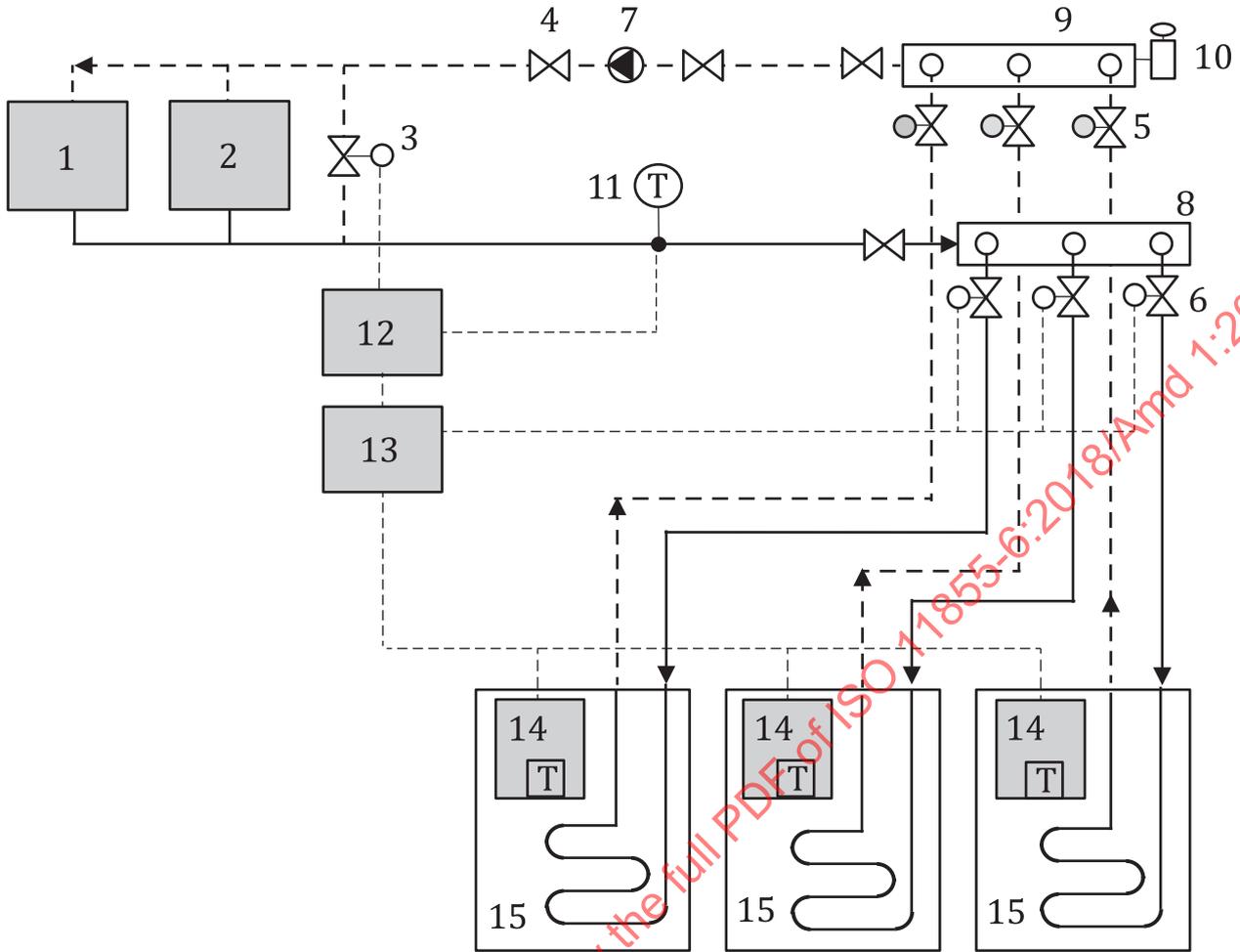
4.5, first paragraph

Modify to the following:

The heat capacity of surfaces with embedded pipes (e.g. as the floor screed), play a significant role for the thermodynamic properties of the heating system and hence for the control strategy. The temperature level of the heat carrier, the time response and the thermal capacity of systems depend on the thickness of the surface layer where the pipes are embedded. The highest capacity involves system types III and V with slow response to load changes on water side in concrete core followed by system types I and II, and the lowest capacity gain systems typed as IV. In most cases, the time constant of the building is several times higher than embedded systems.

Figure A.1

Replace with the following:



Key

- 1 heating generation
- 2 cooling generation
- 3 bypass valve
- 4 valve for maintenance
- 5 balancing valve
- 6 temperature control valve
- 7 pump
- 8 manifold (supply)
- 9 manifold (return)
- 10 air vent
- 11 water temperature sensor
- 12 controller for heat source
- 13 main controller
- 14 room temperature controller
- 15 heating and cooling zone

Figure A.1 — Typical radiant floor header connection